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Part Number: [0740401343](#)
Status: **Active**
Overview: [VHDM Backplane Connector Systems](#)
Description: VHDM Daughtercard, 2.00mm Pitch, 8-Rows, 25 Wafers, 200 Circuits, Tin Lead, Guide Module

Documents:

[Drawing \(PDF\)](#) [Packaging Specification PK-70873-5041-001 \(PDF\)](#)
[Product Specification PS-74031-999-001 \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

UL E29179

General

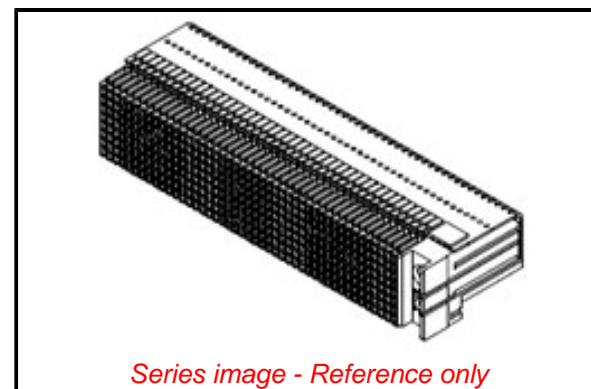
Product Family Backplane Connectors
 Series [74040](#)
 Application Backplane
 Application Tooling Documents TM-622010999
 Comments Daughter Card
 Component Type PCB Header
 Overview [VHDM Backplane Connector Systems](#)
 Product Name VHDM
 UPC 883906551841

Physical

Circuits (Loaded) 200
 Circuits (maximum) 200
 Color - Resin Black
 Durability (mating cycles max) 200
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part Yes
 Keying to Mating Part N/A
 Material - Metal Copper Alloy
 Material - Plating Mating Gold
 Material - Plating Termination Matte Tin
 Material - Resin High Performance Thermoplastic
 Net Weight 59.065/g
 Number of Columns 25
 Number of Pairs N/A
 Number of Rows 8
 Orientation Right Angle
 PC Tail Length 2.80mm
 PCB Locator No
 PCB Retention None
 PCB Thickness - Recommended 1.80mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Plating min - Mating 0.762µm
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55° to +80°C
 Termination Interface: Style Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact 1.0A



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
 D(2020)9139-DC (19
 Jan 2021)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

[74040 Series](#)

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Single Wafer Removal Tool	621004300
Card Stiffener Removal Tool	622016200
Insertion Module	622020214

Data Rate	3.125 Gbps
Shielded	Yes
Voltage - Maximum	120V AC (RMS)/DC

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info**Reference - Drawing Numbers**

Packaging Specification	PK-70873-5041-001
Product Specification	PS-74031-999-001

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